

IN THE SPECIFICATION:

Please amend paragraphs [017], [018], [041] and [069] of the specification as shown below, in which deleted terms are shown with strikethrough and/or double brackets, and added terms are shown with underscoring.

Paragraph [017]       diffusing the element into the base material by heating the base material which is coated with the coating agent ~~substance~~. The metal material can be obtained easily and conveniently by heating after applying the powder with the solvent.

Paragraph [018]       When the base material is a metal material which readily forms an oxide film of, for example, Zn alloy or Al alloy, it is preferable that a reducing agent for reducing the oxide film is applied together with the substance, for the following reason. The oxide film is reduced to disappear under the action of the reducing agent. Therefore, the element can be diffused onto the base material without supplying an extremely large amount of thermal energy.

Paragraph [041]       The most diffused element in the base material 12 of the metal material as described above arrives at a depth from the surface of the base material 12 of at least 0.5 mm (500  $\mu\text{m}$ ). The depth may be 2 cm (2000  $\mu\text{m}$ ) at the maximum. This value is remarkably large as compared with several tens of  $\mu\text{m}$  or about 200  $\mu\text{m}$  of the diffusion distance of the element achieved, for example, by the conventional nitriding and the carburization methods. That is, the diffusion distance of the element achieved in the present invention has the remarkably large value as compared with the diffusion distance of the element by the conventional surface treatment method.

Paragraph [069]      During the process in which the temperature is raised, the reducing agent begins to be decomposed at about 250° C, and carbon and hydrogen are produced. The oxide film formed on the surface of the semimanufactured product disappears as a result of the reduction by the carbon and hydrogen. Accordingly, it is unnecessary for Cu to pass through the oxide film. Therefore, it is possible to shorten the time required for the diffusion, and it is possible to reduce the thermal energy required.